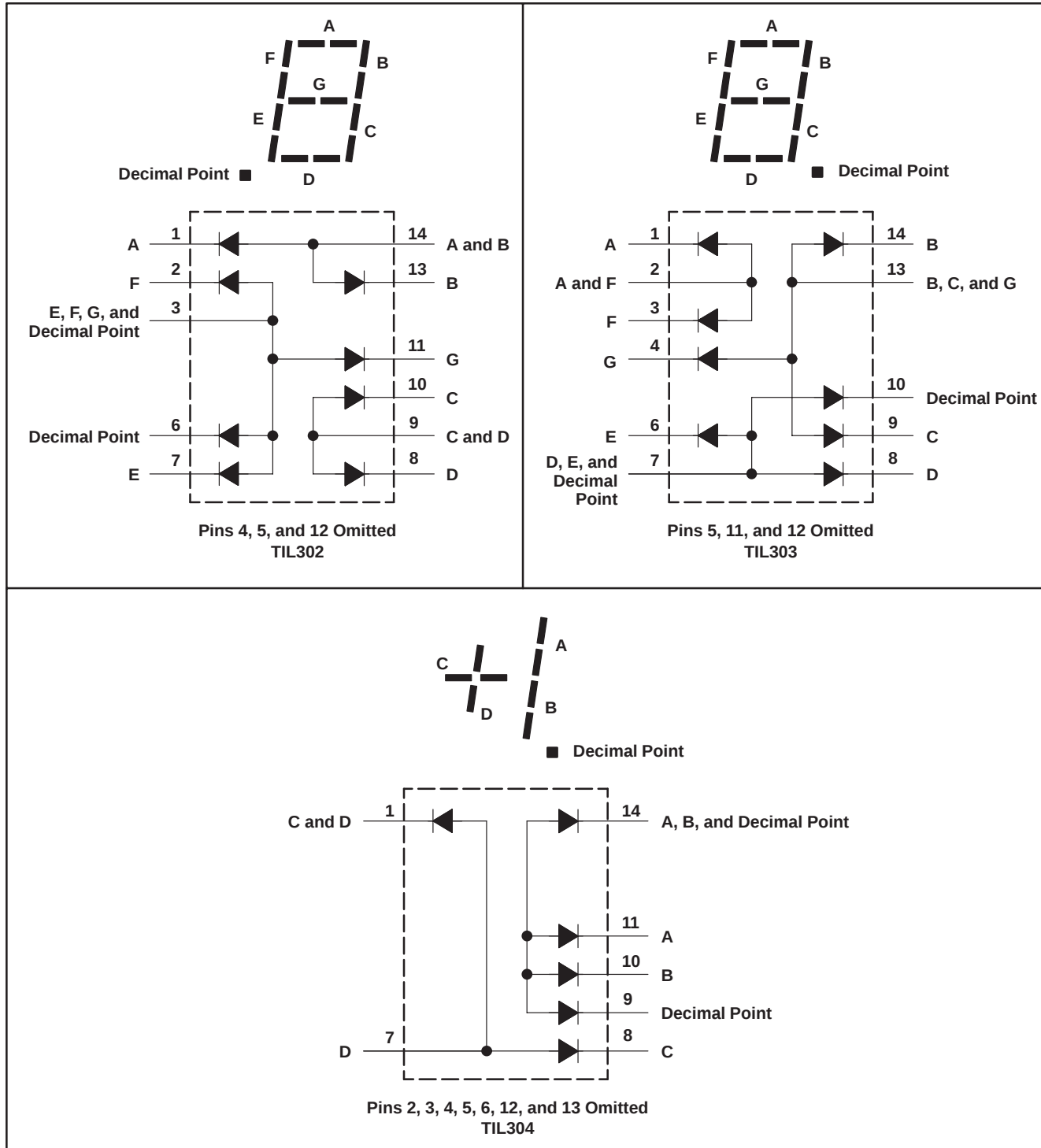


TIL302, TIL303, TIL304 NUMERIC DISPLAYS

SOES010A, APRIL 1971 – REVISED DECEMBER 1993

pin layouts



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Reverse voltage at 25°C free-air temperature:	Each segment	6 V
	Decimal point	3 V
Peak forward current, each segment or decimal point (see Note 1)		200 mA
Continuous forward current:	Each segment or decimal point	30 mA
	Total for TIL302, TIL303	240 mA
	Total for TIL304	150 mA
Operating free-air temperature range, T_A		0°C to 70°C
Storage temperature range		–25°C to 85°C

NOTE 1: This value applies for PRR $\geq$ 60 Hz, duty cycle $\leq$ 10%.

operating characteristics of each segment at 25°C free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
I_V	Luminous intensity (see Note 2)	$I_F = 20$ mA	100	275		μ cd
λ_p	Wavelength at peak emission			660		nm
$\Delta\lambda$	Spectral bandwidth			20		nm
V_F	Static forward voltage		3	3.4	3.8	V
α_{VF}	Average temperature coefficient of static forward voltage	$I_F = 20$ mA, $T_A = 0^\circ\text{C}$ to 70°C		–2.7		mV/°C
I_R	Static reverse current	$V_R = 6$ V			100	μ A
C	Anode-to-cathode capacitance	$V_R = 0$, $f = 1$ MHz		85		pF

operating characteristics of decimal point at 25°C free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
I_V	Luminous intensity (see Note 2)	$I_F = 20$ mA	40	110		μ cd
λ_p	Wavelength at peak emission			660		nm
$\Delta\lambda$	Spectral bandwidth			20		nm
V_F	Static forward voltage		1.5	1.65	2	V
α_{VF}	Average temperature coefficient of static forward voltage	$I_F = 20$ mA, $T_A = 0^\circ\text{C}$ to 70°C		–1.4		mV/°C
I_R	Static reverse current	$V_R = 3$ V			100	μ A
C	Anode-to-cathode capacitance	$V_R = 0$, $f = 1$ MHz		120		pF

NOTE 2: Luminous intensity is measured with a light sensor and filter combination that approximates the CIE (International Commission on Illumination) eye-response curve.

TYPICAL CHARACTERISTICS

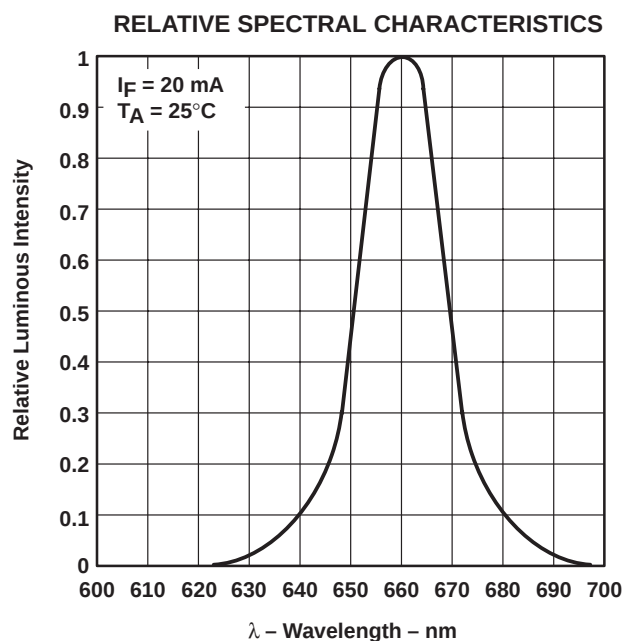


Figure 1

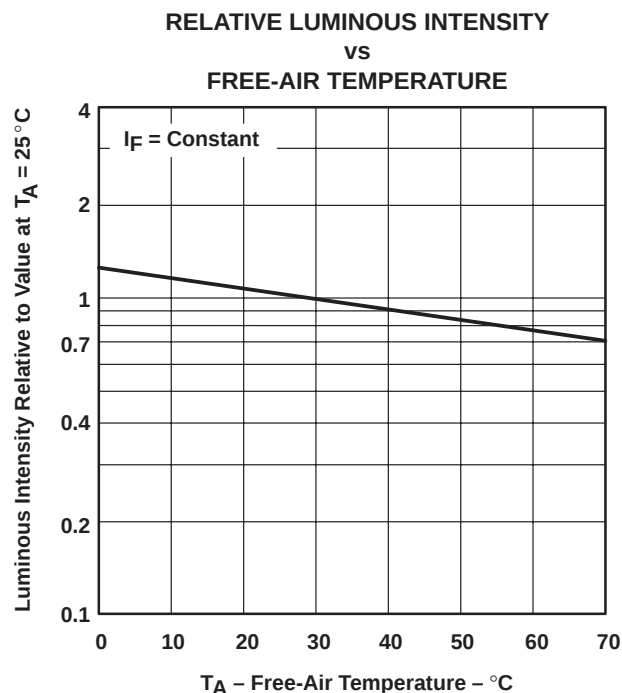


Figure 2

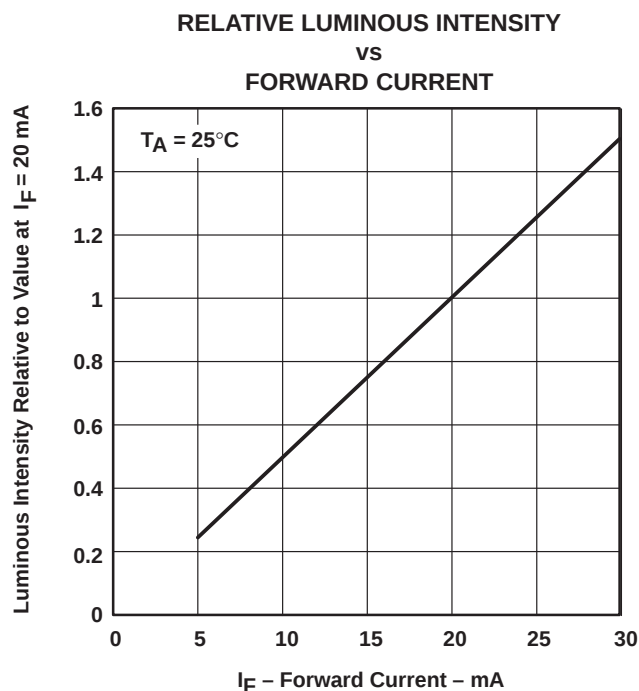


Figure 3

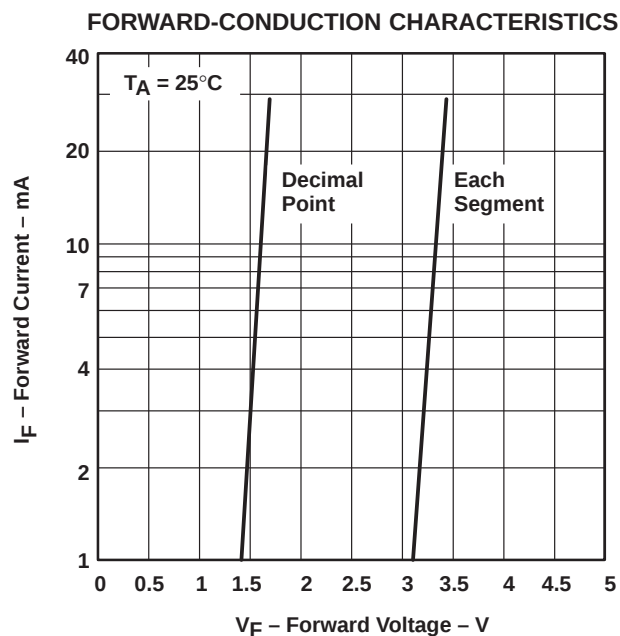
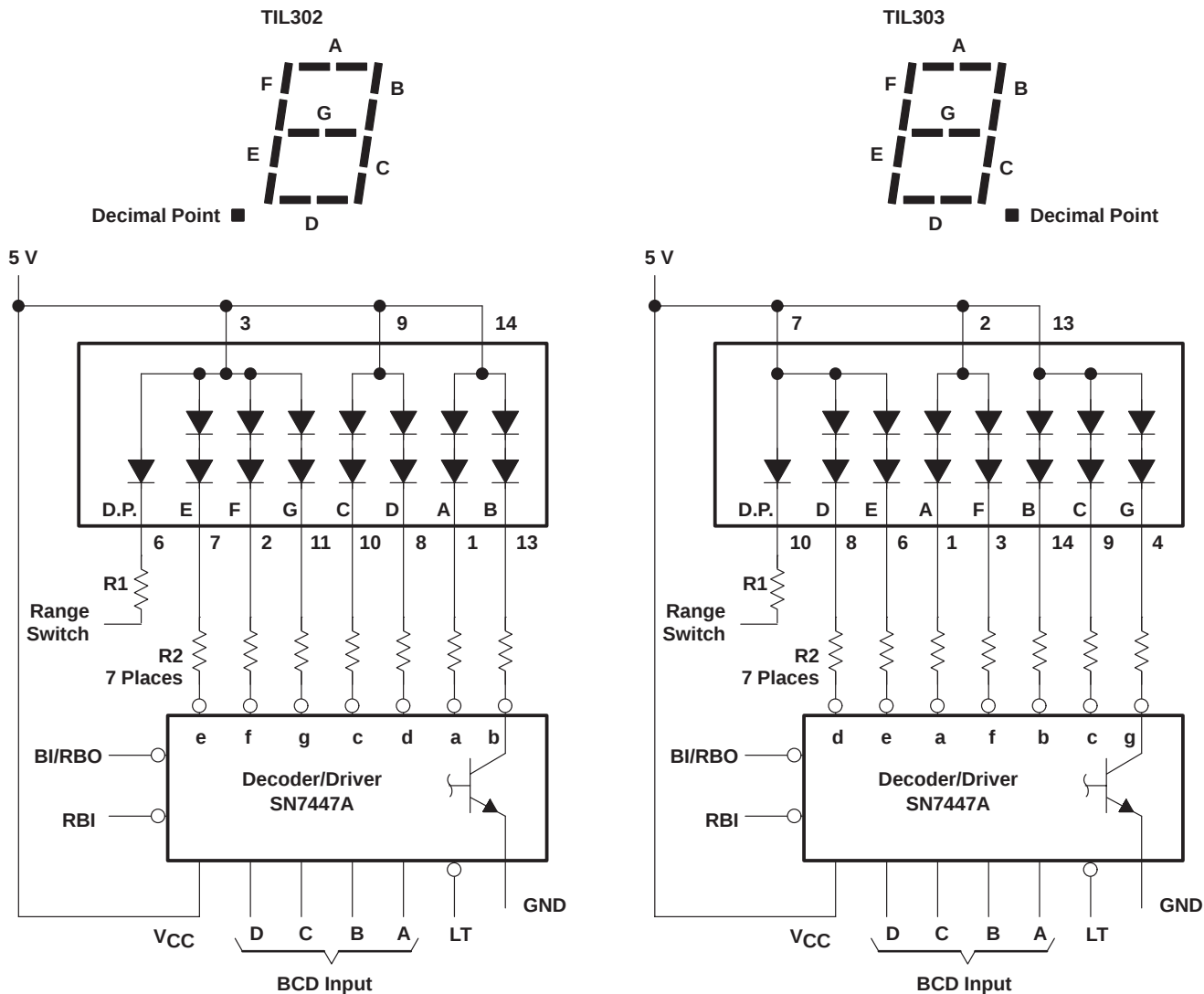


Figure 4

APPLICATION INFORMATION



NOTE A: R1 and R2 are selected for desired brightness.

TIL302, TIL303, TIL304 NUMERIC DISPLAYS

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APPLICATION INFORMATION

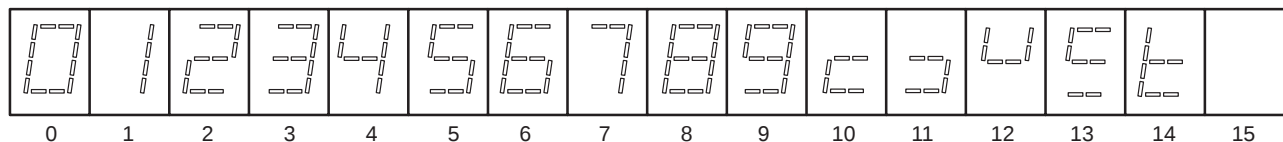
FUNCTION TABLE
SN7447A

DECIMAL OR FUNCTION	INPUTS						BI/RBO†	SEGMENTS							NOTE
	LT	RBI	D	C	B	A		a	b	c	d	e	f	g	
0	H	H	L	L	L	L	H	ON	ON	ON	ON	ON	ON	OFF	1
1	H	X	L	L	L	H	H	OFF	ON	ON	OFF	OFF	OFF	OFF	1
2	H	X	L	L	H	L	H	ON	ON	OFF	ON	ON	OFF	ON	1
3	H	X	L	L	H	H	H	ON	ON	ON	ON	OFF	OFF	ON	1
4	H	X	L	H	L	L	H	OFF	ON	ON	OFF	OFF	ON	ON	1
5	H	X	L	H	L	H	H	ON	OFF	ON	ON	OFF	ON	ON	1
6	H	X	L	H	H	L	H	OFF	OFF	ON	ON	ON	ON	ON	1
7	H	X	L	H	H	H	H	ON	ON	ON	OFF	OFF	OFF	OFF	1
8	H	X	H	L	L	L	H	ON	ON	ON	ON	ON	ON	ON	1
9	H	X	H	L	L	H	H	ON	ON	ON	OFF	OFF	ON	ON	1
10	H	X	H	L	H	L	H	OFF	OFF	OFF	ON	ON	OFF	ON	1
11	H	X	H	L	H	H	H	OFF	OFF	ON	ON	OFF	OFF	ON	1
12	H	X	H	H	L	L	H	OFF	ON	OFF	OFF	OFF	ON	ON	1
13	H	X	H	H	L	H	H	ON	OFF	OFF	ON	OFF	ON	ON	1
14	H	X	H	H	H	L	H	OFF	OFF	OFF	ON	ON	ON	ON	1
15	H	X	H	H	H	H	H	OFF	OFF	OFF	OFF	OFF	OFF	OFF	1
BI	X	X	X	X	X	X	L	OFF	OFF	OFF	OFF	OFF	OFF	OFF	2
RBI	H	L	L	L	L	L	L	OFF	OFF	OFF	OFF	OFF	OFF	OFF	3
LT	L	X	X	X	X	X	H	ON	ON	ON	ON	ON	ON	ON	4

H = high level (logic 1 in positive logic), L = low level (logic 0 in positive logic), X = irrelevant

† BI/RBO is a wire-AND logic serving as a blanking input (BI) and/or ripple-blanking output (RBO).

- NOTES: 1. The blanking input (BI) must be open or held at a high logic level when output functions 0 through 15 are desired. The ripple-blanking input (RBI) must be open or high if blanking of a decimal zero is not desired.
2. When a low logic level is applied directly to the blanking input (BI), all segment outputs are off regardless of any other input.
3. When the ripple-blanking input (RBI) and inputs A, B, C, and D are at a low logic level with the lamp-test input (LT) high, all segment outputs are off and the ripple-blanking output (RBO) of the decoder goes to a low level (response condition).
4. When the blanking input/ripple-blanking output (BI/RBO) is open or held high and a low is applied to the lamp-test input (LT), all segments are illuminated.



NUMERICAL DESIGNATIONS RESULTANT DISPLAYS

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